

AMENDMENTS TO THE CLAIMS

The following listing of claims will replace all prior versions and listings of claims in the application.

LISTING OF CLAIMS

1-4. (Cancelled)

5. (Currently Amended) ~~The method of manufacturing a wiring board as defined in claim 4, further comprising~~A method of manufacturing a wiring board, comprising:

forming on a base material a receiving layer from a thermosetting resin precursor;

forming an interconnecting layer on the receiving layer from a dispersion liquid containing conductive particles;

applying heat to the receiving layer and the interconnecting layer to cure the thermosetting resin precursor and to bond the conductive particles together; and

removing the base material from the receiving layer after curing of the thermosetting resin precursor and bonding of the conductive particles.

6-15. (Cancelled)

16. (Currently Amended) ~~The method of manufacturing a wiring board as defined in claim 15, further comprising~~A method of manufacturing a wiring board, comprising:

forming on a base material a first receiving layer from a thermosetting resin precursor;

forming a first interconnecting layer on the first receiving layer from a dispersion liquid containing conductive particles;

forming a second receiving layer on the first receiving layer and the first interconnecting layer from a thermosetting resin precursor;

forming a second interconnecting layer on the second receiving layer from a dispersion liquid containing conductive particles; and

applying heat to cure the thermosetting resin precursors of the first and second receiving layers and to bond the conductive particles of the first and second interconnecting layers together at a connecting portion of the first and second interconnecting layers;

removing the base material from the first receiving layer after curing the thermosetting resin precursors of the first and second receiving layers and bonding of the conductive particles of the first and second interconnecting layers at a connecting portion of the first and second interconnecting layers.

17-19. (Cancelled)